EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L20	2	("6429096").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 09:46
L21	2	("6627988").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 09:48
L22	10	("20010009302" | "5229643" | "5554887" | "5903052" | "5920117" | "6184580" | "6219243" | "6259156"). PN. OR ("6627988").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/11 09:47
L23	2	("6376769").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 09:58
L24	91	("3555364" | "4734825" | "5043794" | "5148265" | "5172303" | "5192716" | "5286926" | "5347159" | "5367764" | "5371654" | "5375041" | "5386341" | "5394303" | "5473119" | "5483421" | "5548091" | "5558928" | "5570504" | "5583321" | "5665473" | "5672548" | "5682061" | "5685885" | "5686699" | "5734555" | "5777379" | "5783870" | "5794330" | "5798564" | "5801439" | "5848467" | "5861666" | "5875545" | "5901041" | "5915170" | "5926369" | "5929517" | "5943213" | "5950304" | "6108210").PN. OR ("6376769"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/11 09:51
L25	2	("6673651").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 09:59
L26	15	("5239198" | "5668405" | "5866949" | "5880590" | "5895965" | "5925934" | "6031292" | "6083776" | "6166443" | "6201302" | "6229215" | "6259154" | "6326696" | "6404049").PN. OR ("6673651").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/11 10:03

L27	2	("6673651").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 10:03
L28	2	"20020070458"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/11 10:03
L29	75	("4413308" | "4581680" | "4641222" | "4707657" | "5077598" | "5137461" | "5148266" | "5258330" | "5352926" | "5367435" | "5369551" | "5414298" | "5435732" | "5450290" | "5451720" | "5453580" | "5473120" | "5477082" | "5477933" | "5483421" | "5491303" | "5509815" | "5586010" | "5598033" | "5690270" | "5700549" | "5738531" | "5800184" | "5829988" | "5880890").PN. OR ("6050832"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/11 10:33
L31	55	@ad<="20040330" and "flexible" with interposer with solder with ball	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/11 10:42
L32	48	@ad<="20040330" and "flexible" with interposer with "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/11 11:03
L33	25	@ad<="20040330" and "flexible interposer" same "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/11 11:49
L34	2	("6830463").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/11 11:49
S1	2	"20040201096"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:03
S2	2289	@ad<="20040330" and (257/678). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:13

S3	2099	@ad<="20040330" and (257/697-698).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:04
S4	1585	@ad<="20040330" and (257/700).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:04
S5	1913	@ad<="20040330" and (257/784).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:38
S6	1756	@ad<="20040330" and (257/786).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:07
S7	10	@ad<="20040330" and 'flexible' same 'wiring circuit' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:16
S8	1	"6580031".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:10
S9	1	"6580031".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:11
S10	6144	@ad<="20040330" and (361/749-750).ccls. or (361/760).ccls. or (361/792).ccls. or (361/795).ccls. or (257/686).ccls. or (257/685).ccls. or (257/688).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:16
S11	21	@ad<="20040330" and 'flexible' same 'wiring substrate' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:20
S12	864	S10 and 'flexible' with 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:17
S13	235	@ad<="20040330" and 'wiring substrate' and 'solder ball' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:38
S14	1	"6285081".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:30
S15	1	"6181569".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:30

S16	1	"6114187".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:31
S17	1	"6005292".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:31
S18	1	"5900738".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S19	1	"5414371".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S20	1	"5086337".PN.	USPAT; USOCR	OR	ON	2005/10/20 09:33
S21	3938	@ad<="20040330" and (257/773-774).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 09:38
S22	931	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:15
S23	6	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal stud'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:15
S24	10	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'stud'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:16
S25	8	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'plug'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 10:16
S26	180	@ad<="20040330" and ('wiring board' or 'wiring tape') and 'solder ball' and ('printed circuit board' or 'PCB') and 'metal' with 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:15
S27	2	("6329610").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 10:56
S28	9	(("5811982") or ("5914614") or ("6329827") or ("6722032")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 11:08

S29	1	"5177438".PN.	USPAT; USOCR	OR	ON	2005/10/20 10:58
S30	1	"5576630".PN.	USPAT; USOCR	OR	ON	2005/10/20 10:58
S31	4	(("6288905") or ("6376769")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 11:08
S32	951	@ad<="20040330" and 'flexible' with 'substrate' and 'copper' and 'solder ball' and ('printed circuit board' or 'PCB')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:16
S33	353	@ad<="20040330" and 'flexible' with 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:16
S34	51	@ad<="20040330" and 'wiring substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25
S35	233	@ad<="20040330" and 'wiring board' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:17
S36	4	@ad<="20040330" and 'wiring tape' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:17
S37	0	@ad<="20040330" and 'flxibel' same 'substrate' and 'copper' with 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25
S38	0	@ad<="20040330" and 'flxibel' same 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:25
S39	0	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' with 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:26

S40	425	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:28
S41	6	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' same 'pillar' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:26
S42	105	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' same 'bump' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:57
S43	5	@ad<="20040330" and 'flexible' same 'substrate' and 'copper' with 'stud' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 11:28
S44	1	"6010769".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:36
S45	1	"5876842".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:39
S46	1	"5744758".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:39
S47	1	"5600103".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:40
S48	1	"5510216".PN.	USPAT; USOCR	OR	ON	2005/10/20 11:40
S49	67	@ad<="20040330" and 'tape' same 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12
S50	2	("6081026").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/20 12:06
S51	1	"5854534".PN.	USPAT; USOCR	OR	ON	2005/10/20 12:09
S52	96	@ad<="20040330" and 'flexible' same 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12
S53	80	@ad<="20040330" and 'flexible' with 'interposer' and 'copper' and 'solder ball' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/20 12:12

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S54	2	@ad<="20040330" and "wiring substrate" same "solder ball" same "PCB"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:39
S55	1267	@ad<="20040330" and "wiring substrate" same ("solder ball" or "bump")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:39
S56	13	@ad<="20040330" and "wiring substrate" same ("bump") same "plug"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:41
S57	1032	@ad<="20040330" and "wiring substrate" same "bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:41
S59	1234	@ad<="20040330" and "wiring board" same "solder bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:41
S60	246	@ad<="20040330" and "wiring board" with "bump" same "copper"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:45
S61	101	@ad<="20040330" and "wiring circuit board" with "bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:50
S62	2	@ad<="20040330" and "wiring circuit board" and "plug" with "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:51
S63	16	@ad<="20040330" and "wiring circuit board" and "metal" with "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:51
S64	30	@ad<="20040330" and "wiring circuit board" and "bump" with "solder ball"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 11:51